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(54) **GROUNDING RING OF A PROCESS KIT FOR SEMICONDUCTOR SUBSTRATE PROCESSING**

37/32897; H01J 37/3414; H01J 37/3423;
H01L 21/00; H01L
(Continued)

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(**) Term: **15 Years**

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(51) **LOC (15) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D15/138; D13/182**

(58) **Field of Classification Search**
USPC D15/138, 140, 141, 144, 144.1, 144.2, D15/199; D13/118, 182, 184, 199
CPC H01J 37/32623; H01J 37/32633; H01J 37/32642; H01J 37/32715; H01J 37/32733; H01J 37/32743; H01J

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(57) **CLAIM**

The ornamental design for a grounding ring of a process kit for semiconductor substrate processing, as shown and described.

DESCRIPTION

FIG. 1 is a top isometric view of a grounding ring of a process kit for semiconductor substrate processing, according to the novel design.
FIG. 2 is a bottom isometric view thereof.
FIG. 3 is a top plan view thereof.
FIG. 4 is a bottom plan view thereof.
(Continued)

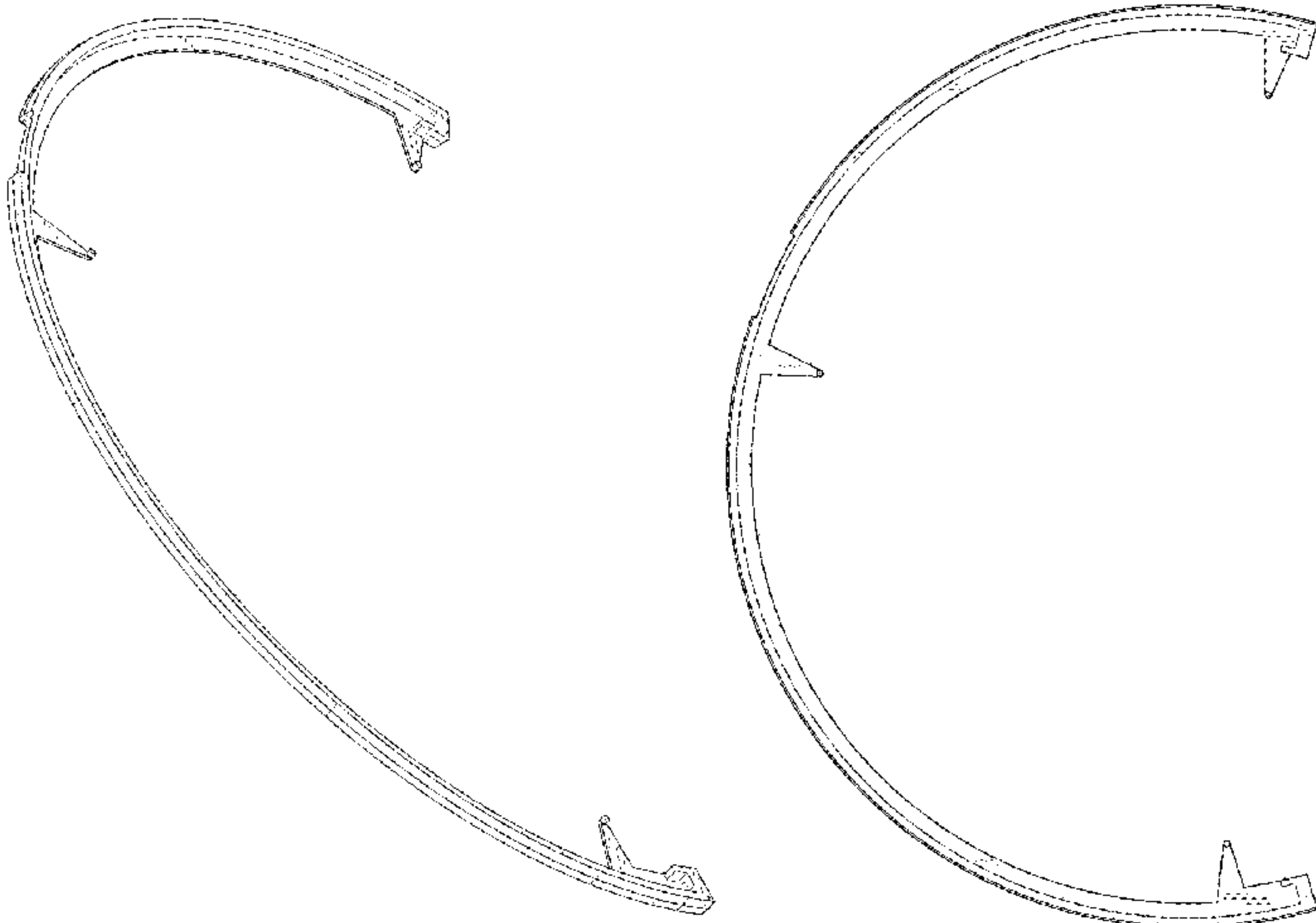


FIG. 5 is a left elevation view thereof.
FIG. 6 is a right elevation view thereof.
FIG. 7 is a back elevation view thereof, enlarged to more clearly show details; and,
FIG. 8 is a front elevation view thereof, enlarged to more clearly show details.

1 Claim, 6 Drawing Sheets

(58) Field of Classification Search

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See application file for complete search history.

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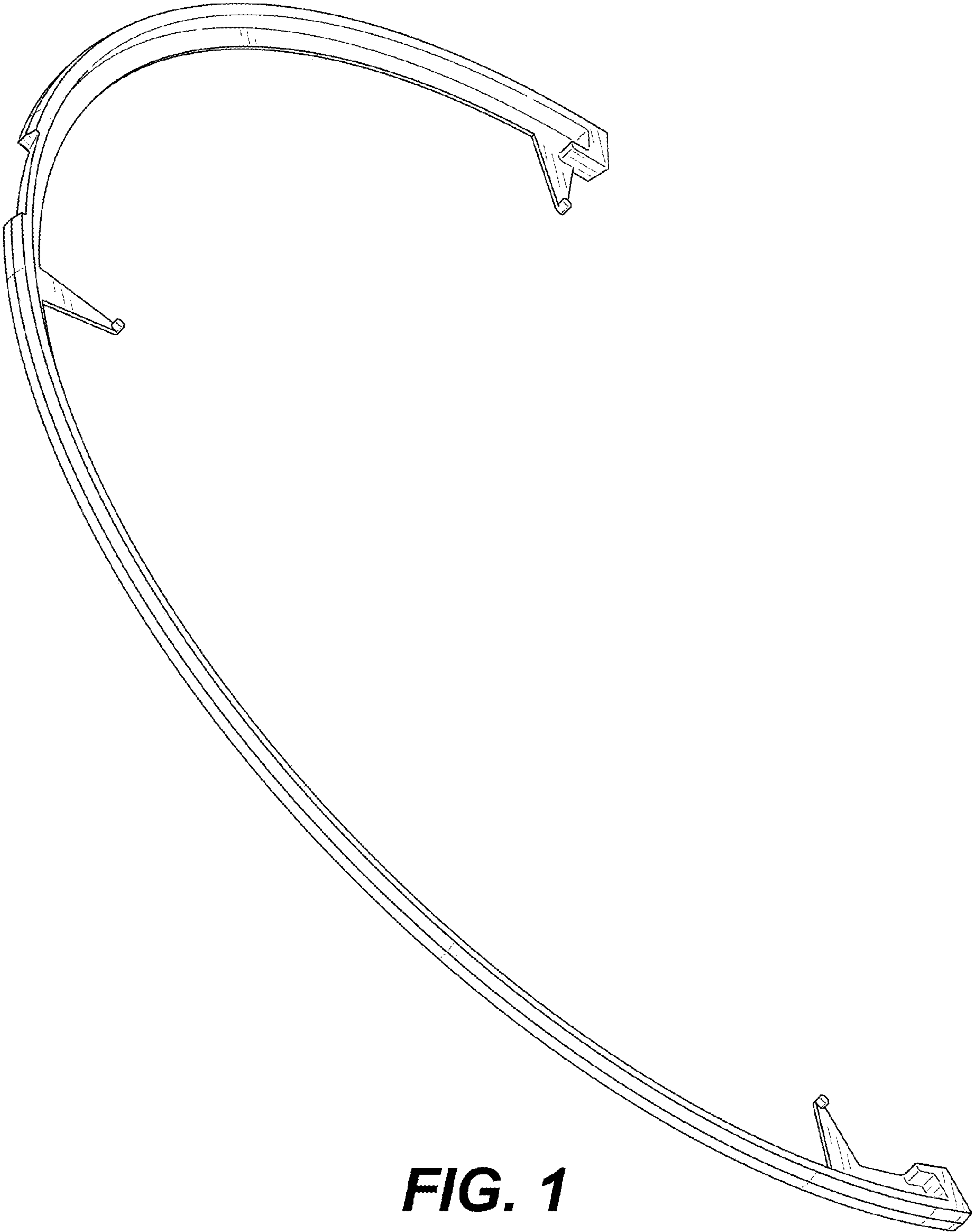


FIG. 1

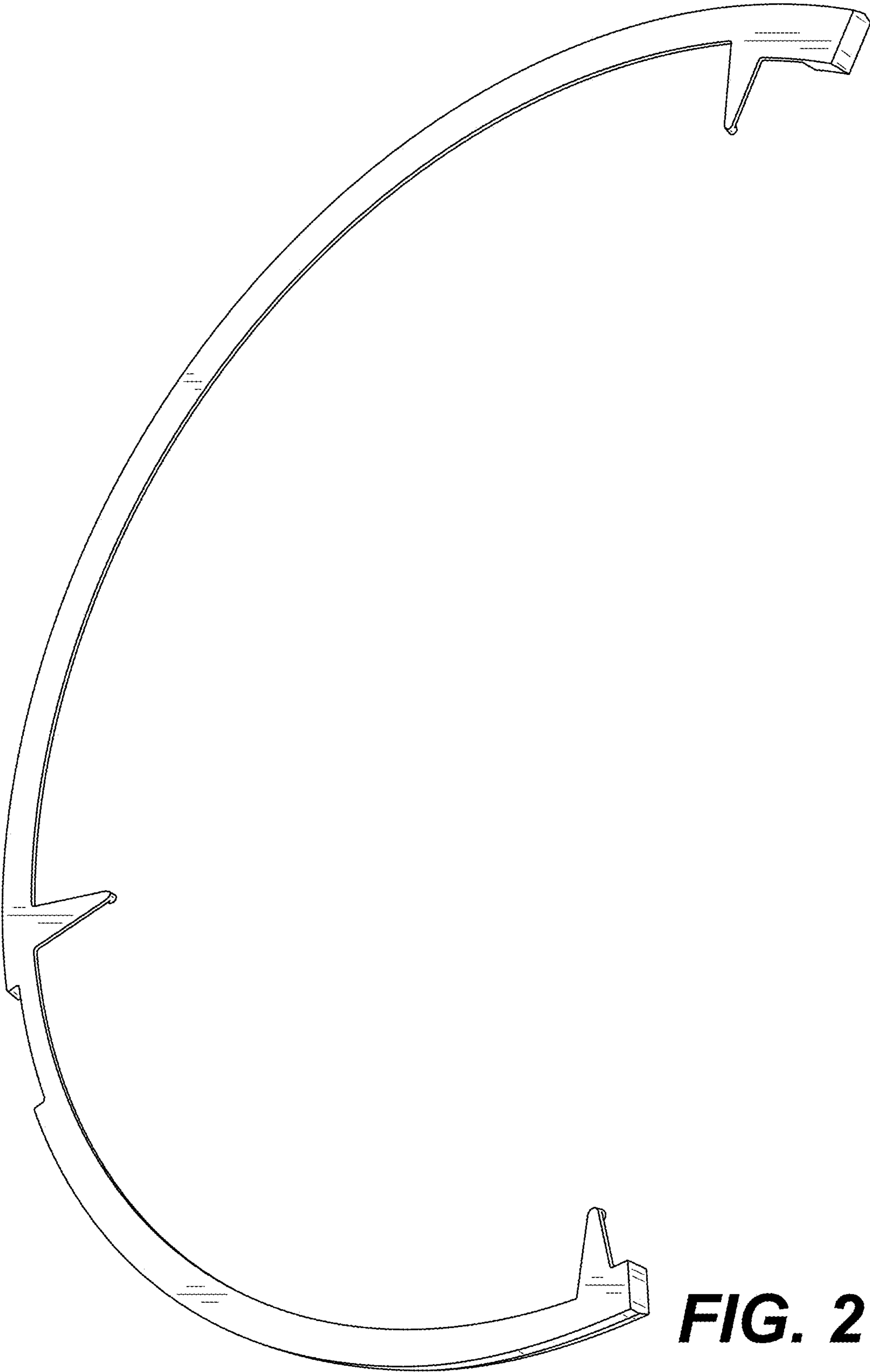


FIG. 2

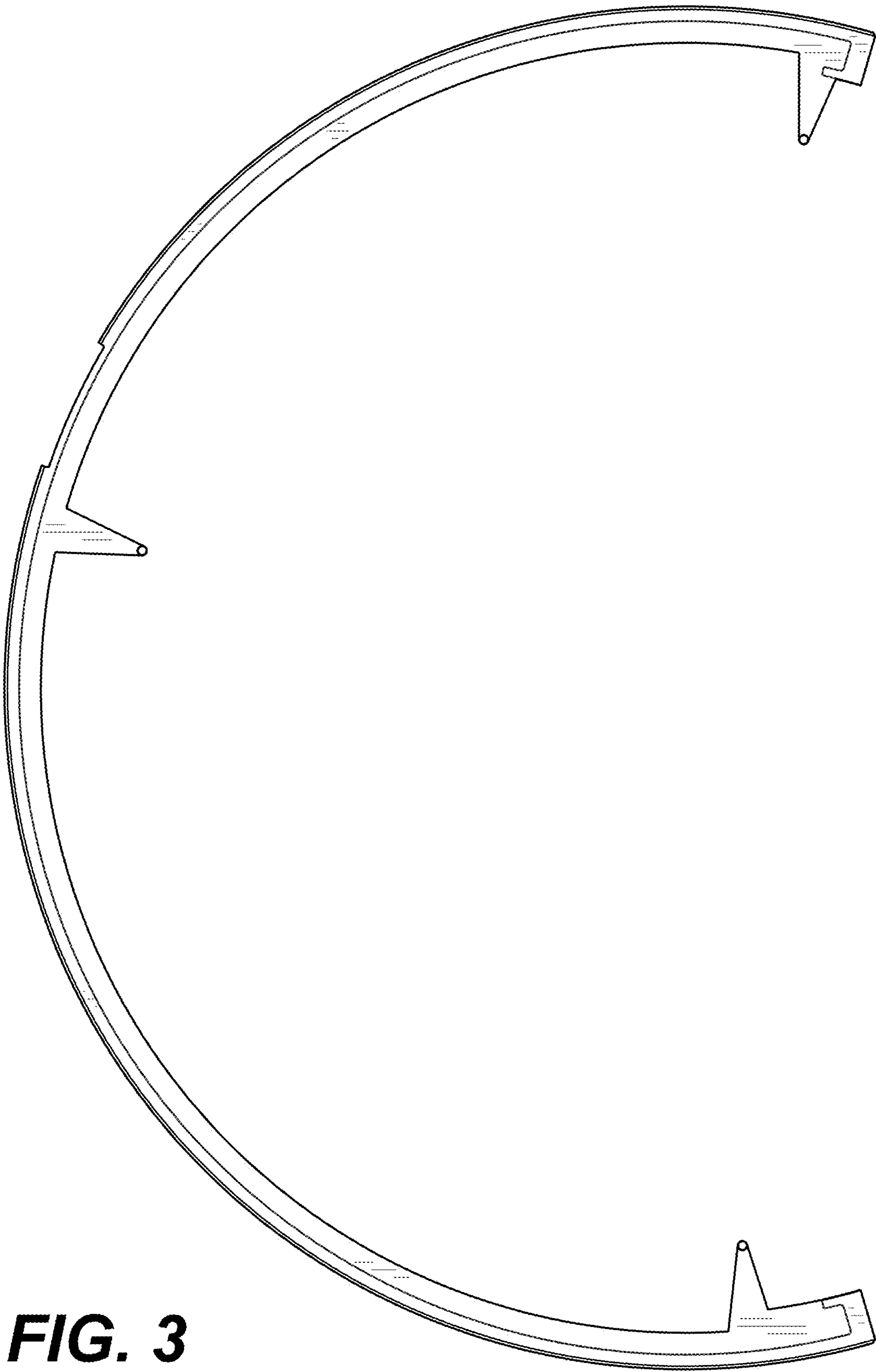


FIG. 3

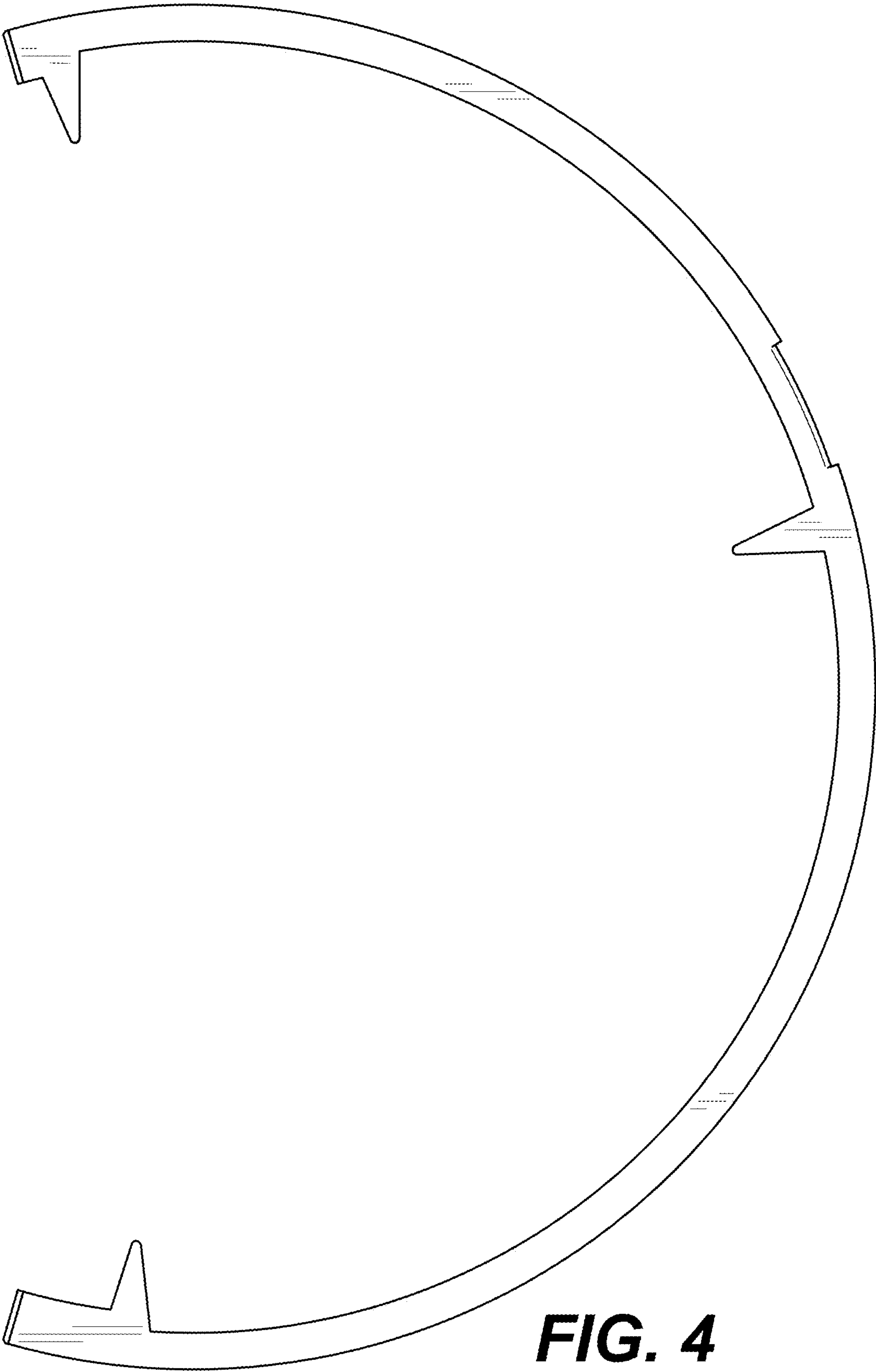




FIG. 5



FIG. 6



FIG. 7



FIG. 8